



Silicon-based Transmitter Design for Optical Fiber Communications

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Outline

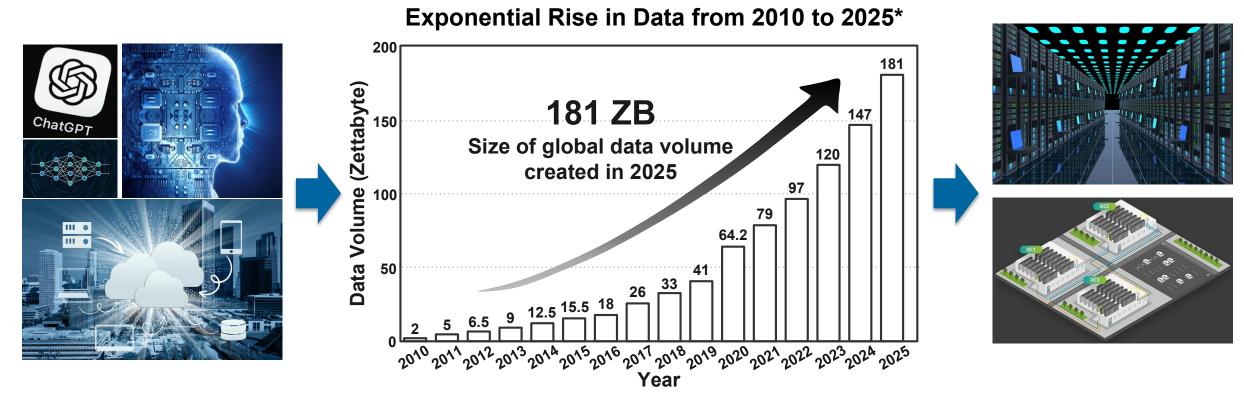
- Background
- Transmitter Design for VCSEL-based Optical Links
 - Imperfections of VCSEL
 - Implementation and Measurement of A 56-Gb/s PAM-4 VCSEL Transmitter
- Transmitter Design for Optical Modulator-based Optical Links
 - Design Challenges
 - Implementation and Measurement of A 56-Gbaud Linear Modulator Transmitter
 - Implementation and Measurement of A 100-Gbaud Linear Modulator Driver
- Conclusions

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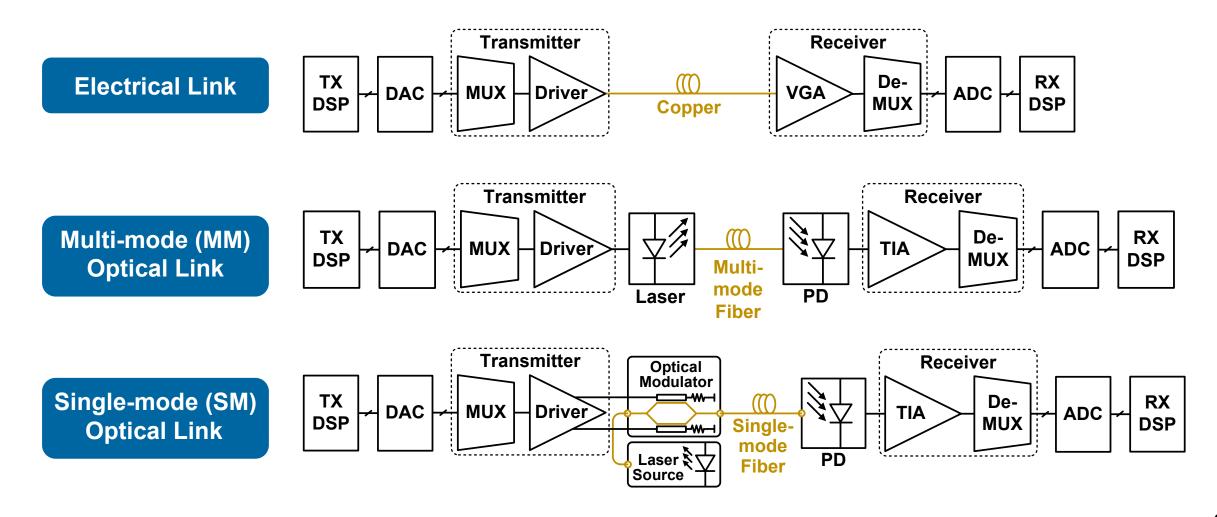
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Research Background

- Cutting-edge information technologies create massive data volume
- Data center interconnects to be upgraded towards higher data rate and better energy efficiency

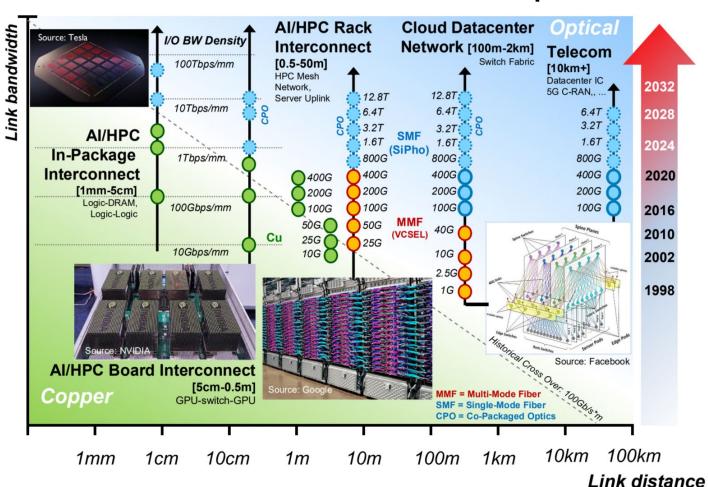


Electrical vs MM Optical vs SM Optical Links



Electrical vs MM Optical vs SM Optical Links

Wireline Interconnect Roadmap*



Electrical Link

- High loss, low bandwidth
- Low cost
- Distance-data rate product (DDP) < 100 Gb/s*m

MM Optical Link

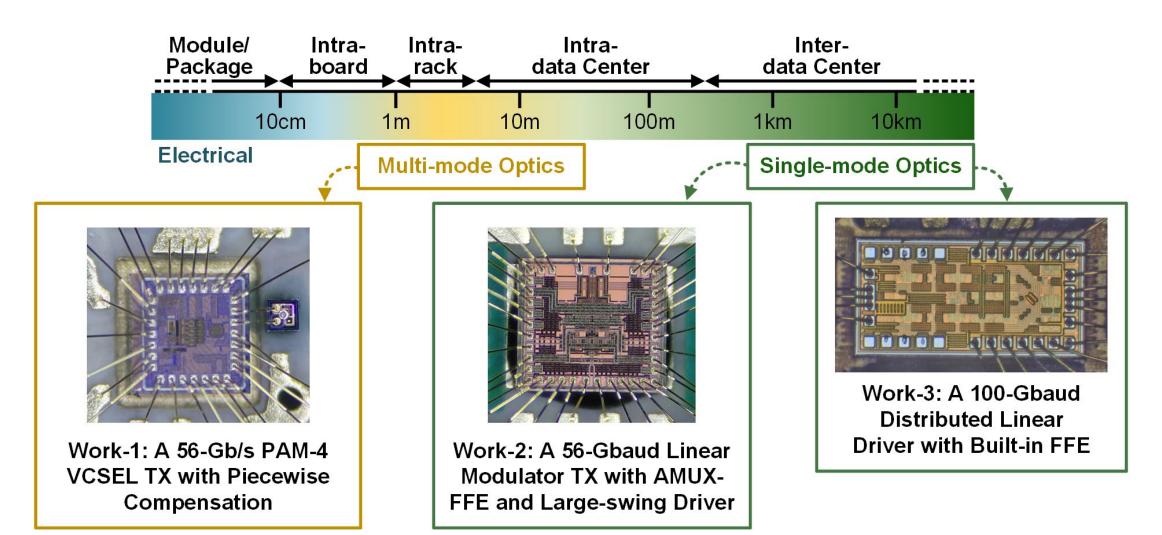
- Low loss, high bandwidth
- Moderate cost, dispersion issue
- 100 Gb/s*m < DDP < 4000 Gb/s*m

SM Optical Link

- Low loss, high bandwidth, low dispersion
- High cost
- 4000 Gb/s*m < DDP

(*Joris Van Campenhout, "Silicon Photonics Technology for Next-Generation Transceivers," in *ISSCC 2022 Forum 4*, Feb. 2022.)

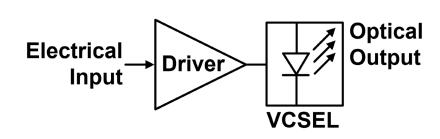
Thesis Scope



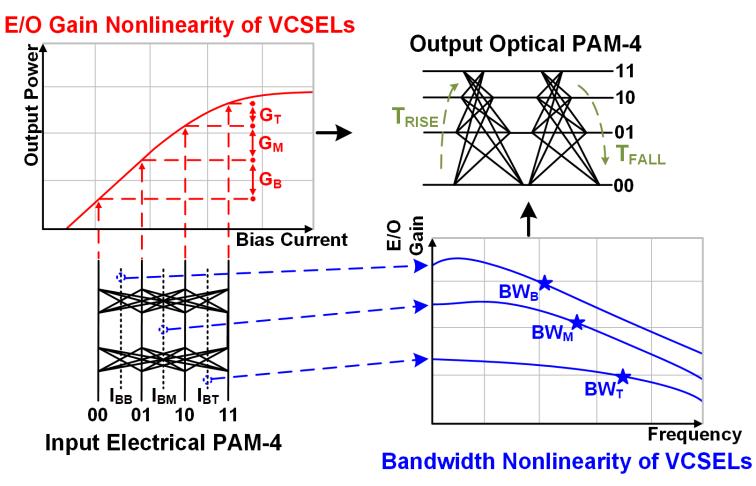
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Imperfections of VCSEL



- Bias current ↑, E/O gain ↓
 (G_B > G_M > G_T)
- Bias current ↑, bandwidth ↑
 (BW_B < BW_M < BW_T)
- T_{RISE} < T_{FALL}

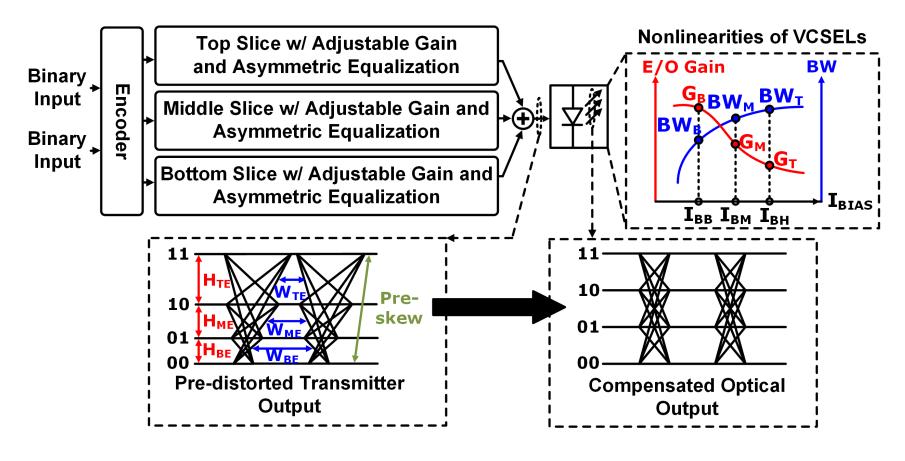


Outline

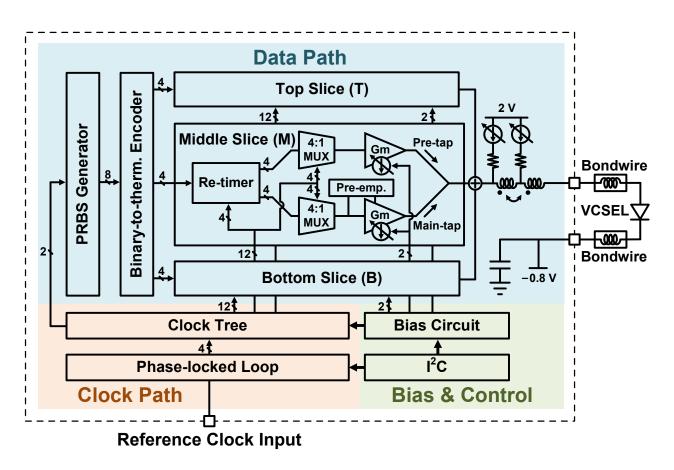
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 - Implementation and Measurement of A 100-Gbaud Distributed Linear Driver
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Conceptual Architecture

Thermometer code-based architecture to piecewise compensate for nonlinearity in E/O gain, nonlinearity in bandwidth, and asymmetric responses to rising/falling transitions



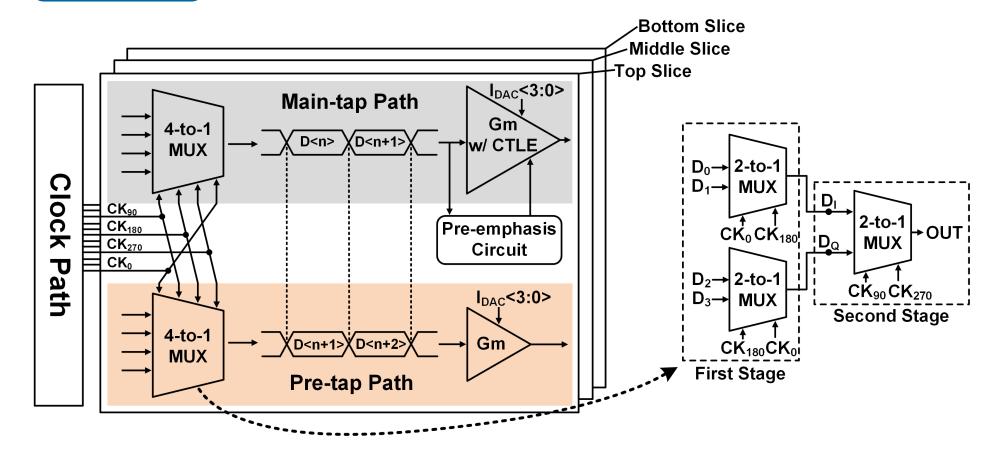
Detailed Architecture



- Data path
 - 2-tap feed-forward equalizer
 - Gm cell-merged CTLE
 - Pre-emphasis circuit
- Clock path
 - Wideband phase-locked loop
 - Clock tree with cascading VCDLs
- Bias & control part
- Optical part
 - Wire-bonded anode-driven VCSEL
 - Negative bias for power saving

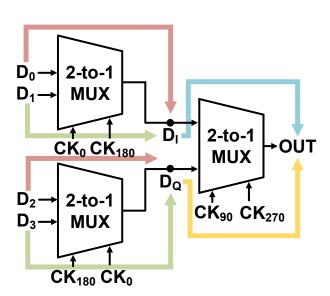
Functions of 4-to-1 MUX

- 4 quarter-rate data streams → 1 full-rate data stream
- Controls tap interval of the 2-tap FFE

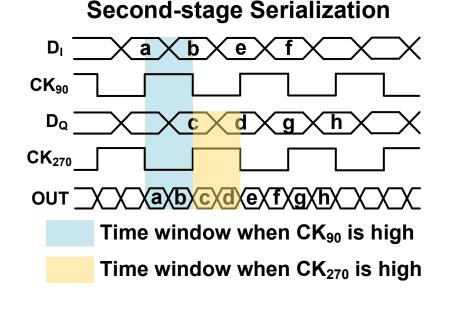


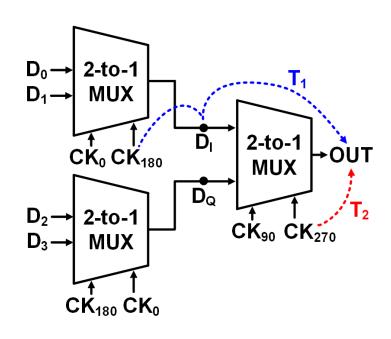
Principle of 4-to-1 MUX

- Implemented by cascading two-stages of 2-to-1 MUXs
- 1st-stage 2-to-1 MUX serializes D₀~D₁ to D₁ and D_Q
- 2nd-stage 2-to-1 MUX further serializes D_I and D_O to OUT

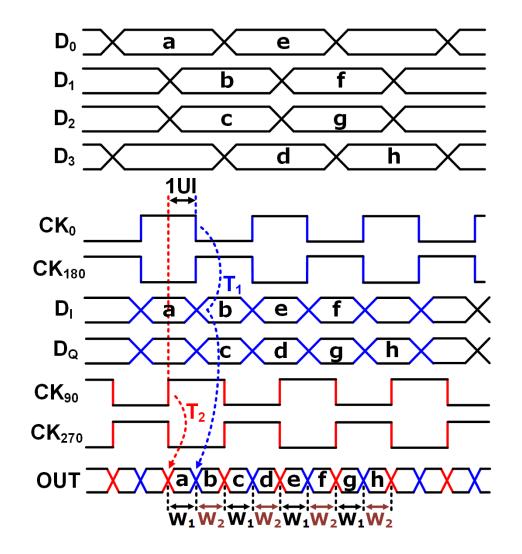


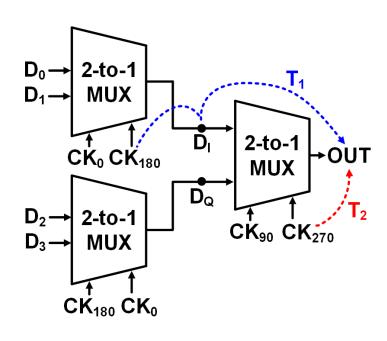
First-stage Serialization CK₀ CK₁₈₀ D_Q Time window when CK₀ is high Time window when CK₁₈₀ is high



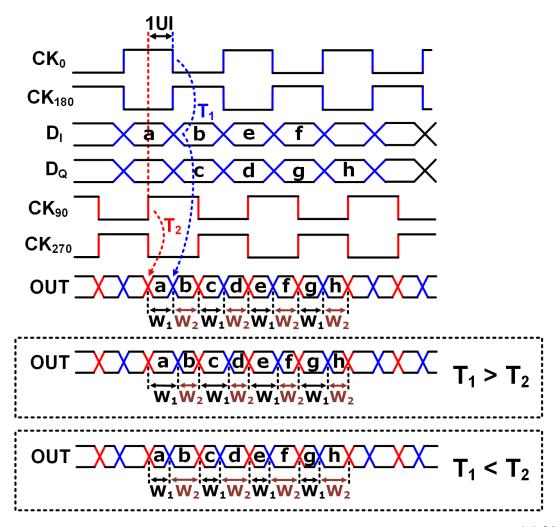


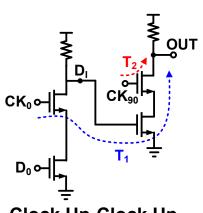
- T₁: Delay from CK₀ (CK₁₈₀) to OUT
- T₂: Delay from CK₉₀ (CK₂₇₀) to OUT
- $T_1 \neq T_2 \rightarrow Duty Cycle Distortion of the Output$



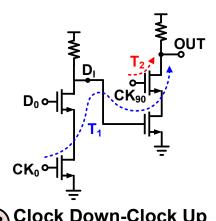


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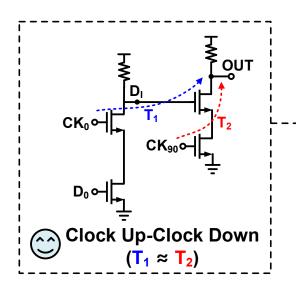


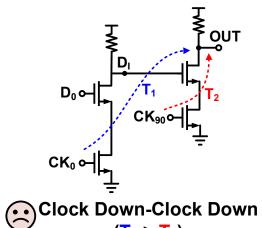


Clock Up-Clock Up $(T_1 > T_2)$

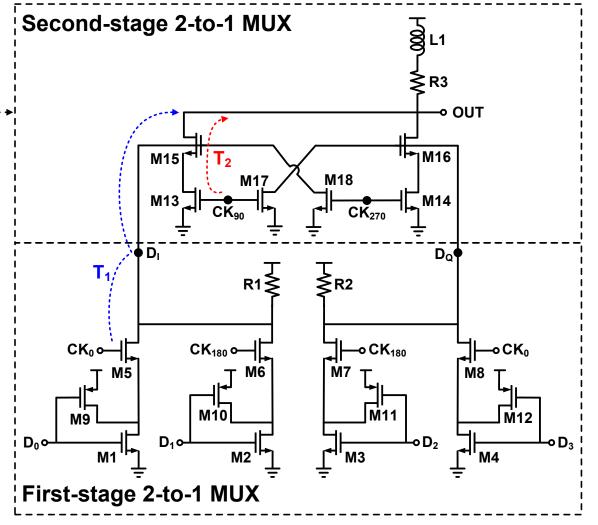


 $(T_1 >> T_2)$





 $(\mathsf{T}_1 > \mathsf{T}_2)$

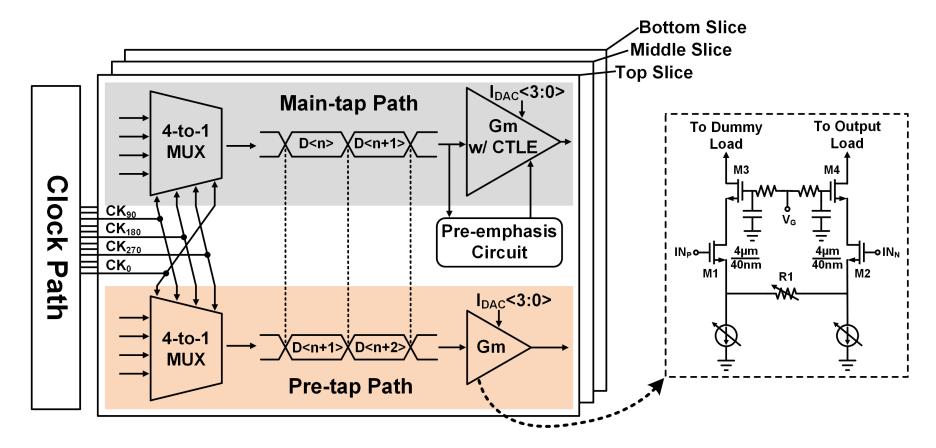


Output Driver

Design of Pre-tap

Gm Cell

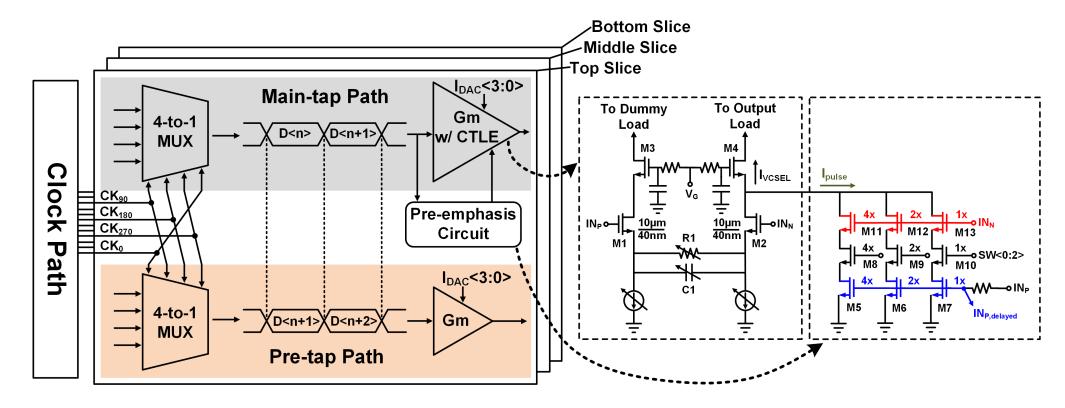
- Cascode structure for preventing breakdown issue
- Tunable tail current source for gain adjustment



Output Driver

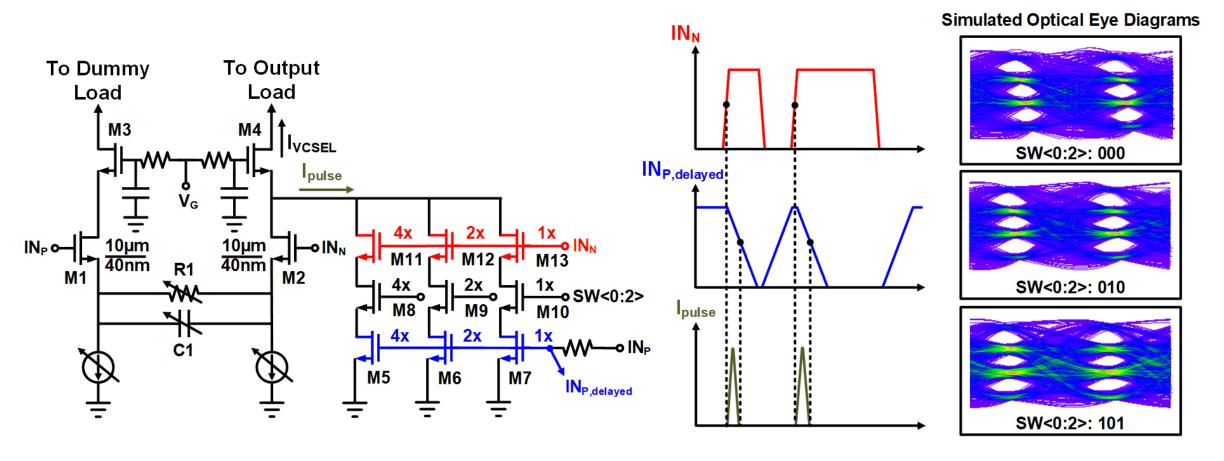
Design of Main-tap Gm Cell

- Transistors size 2.5 times larger than pre-tap Gm cell
- Source-degenerated capacitor for BW extension
- Pre-emphasis circuit for mitigating optical eye skew

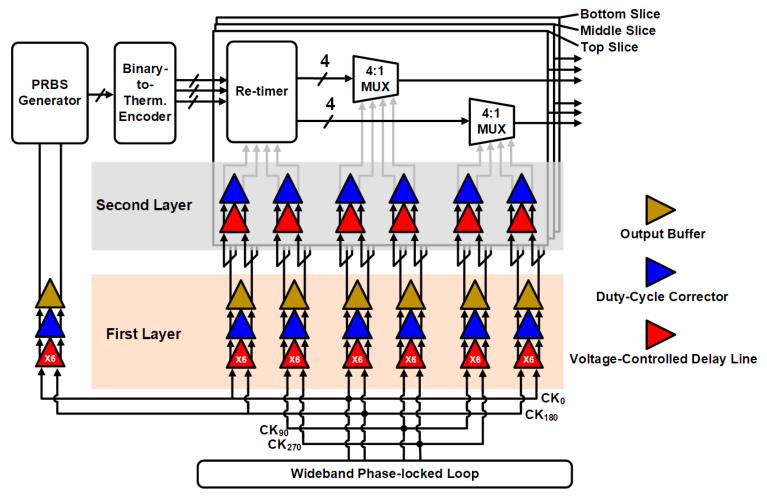


Output Driver

• $IN_N \uparrow \rightarrow I_{VCSEL} \downarrow \rightarrow IN_N \& IN_{P,delayed}$ both high \rightarrow A sharp current pulse I_{pulse} generated



Clock Tree



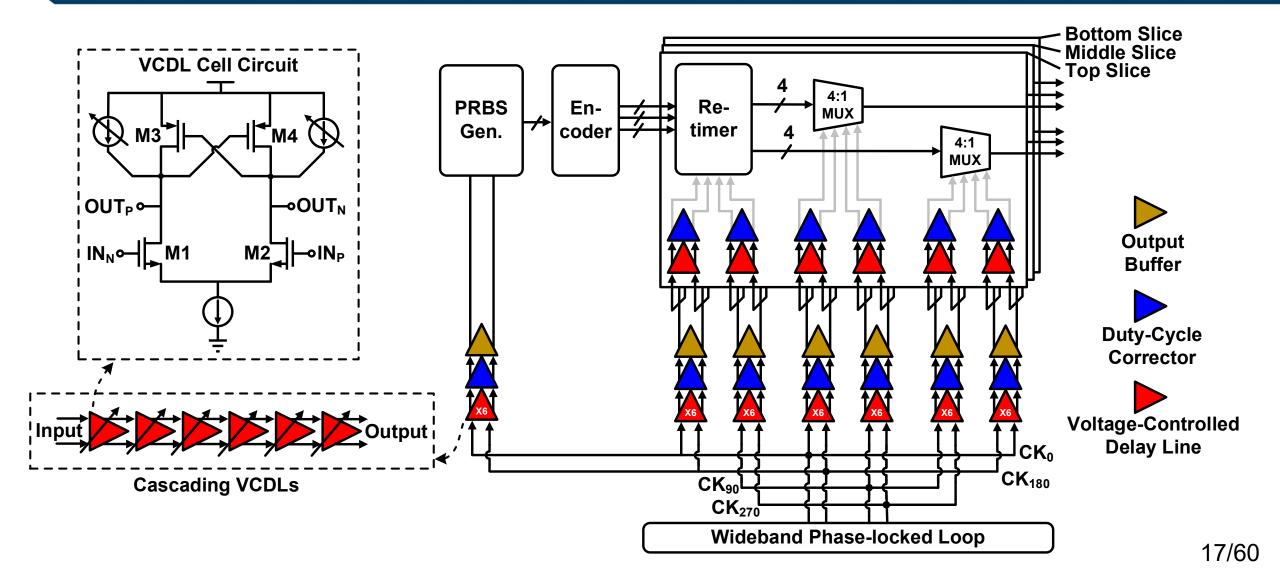
1st-Layer Clock Tree

 Aligns the timing between the PRBS generator, re-timer and 4to-1 MUXs

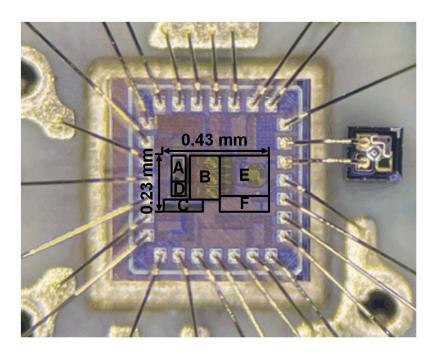
2nd-Layer Clock Tree

 Mitigates the timing skew between the three slices

Clock Tree

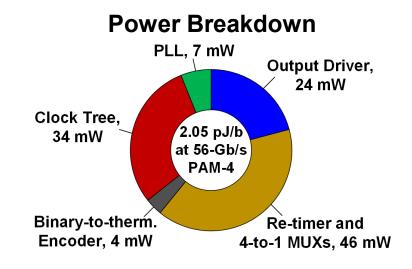


Design Under Test



- A PRBS Generator + Binary-to-therm. Encoder
- B Re-timer + 4-to-1 Multiplexers
- C Phase-locked Loop
- D Clock Tree
- **E** Output Driver
- F Bias Circuit + I²C

- Fabricated in 40-nm bulk CMOS
- Transmitter core occupies 0.1 mm²
- Consumes 115 mW at 56-Gb/s PAM-4

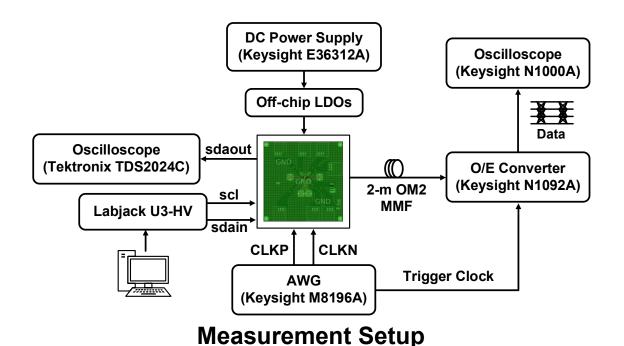


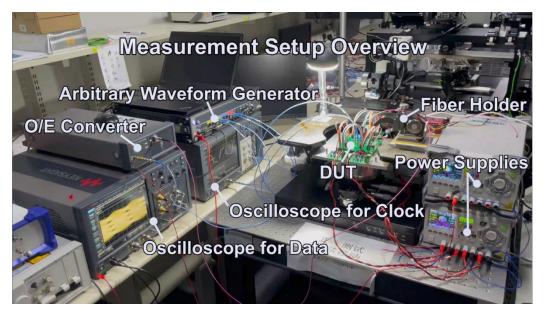
Measurement Setup

- A commercial VCSEL is wire-bonded with the transmitter for optical measurements
- The optical signal is butt-coupled to the multi-mode fiber



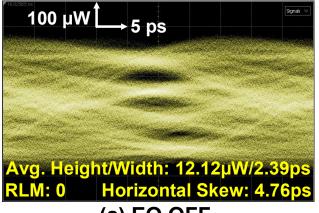
Scan to Visit Measurement Video



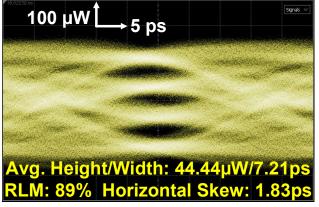


Measurement Environment

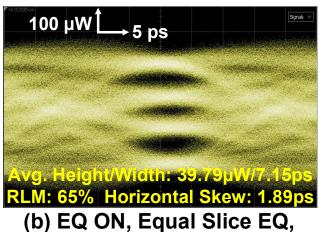
Measurement Results

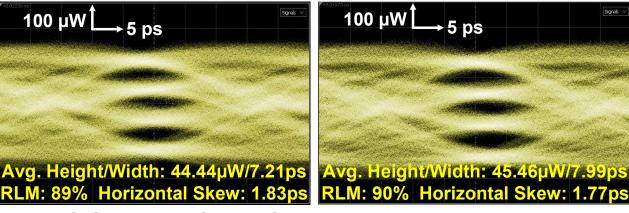






(c) EQ ON, Equal Slice EQ, **Piecewise Tuned Slice Gain**

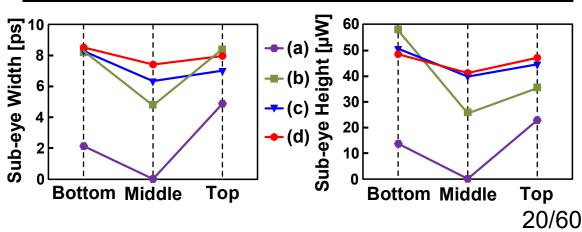




Equal Slice Gain

(d)	EQ	ON,	Piece	ewise	Tunned
	Slic	e EQ	and	Slice	Gain

	(a)	(b)	(c)	(d)
Average Sub-Eye Height [µW]	12.12	39.79	44.44	45.46
Average Sub-Eye Width [ps]	2.39	7.15	7.21	7.99
Ratio-of-Level Mismatch	0	65%	89%	90%
Horizontal Skew [ps]	4.76	1.89	1.83	1.77



Comparison with Prior Works

	[2] PTL'18	[3] JSSC'22	[4] VLSI'19	[5] ASSCC'21	[1] This work
CMOS Node [nm]	65	40	65	40	40
Architecture Signaling Scheme	1/2-rate PAM-4	1/4-rate PAM-4	1/4-rate PAM-4	1/4-rate PAM-4	1/4-rate PAM-4
Data Rate [Gbps]	50	56	64	64	56
OMA [mW]	2.00	0.81*	2.50*	1.08*	1.18*
Power effi. [pJ/b]	5.12	1.73	2.69#	2.09	2.05#
Core Area [mm ²]	0.31	0.47	0.28	0.16	0.10
Asymmetric Equalization	2.5-tap DAC- based FFE	2-tap DAC-based FFE	3-tap LSB/MSB- based Asymmetric FFE	3-tap LSB/MSB- based Asymmetric FFE	2-tap FFE + CTLE + Pre-emphasis
Imperfection Compensation	Full	Full	Partial	Partial	Full
Method Type	Digital	Digital	Analog	Analog	Mixed-signal

^{*3-}dB butt coupling loss de-embedded [6]

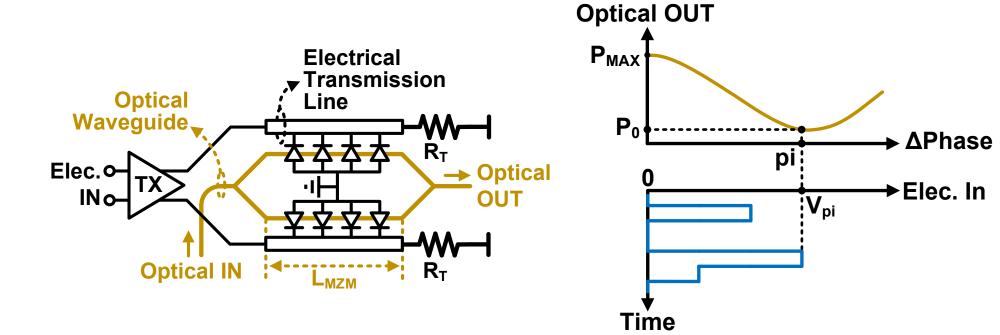
[#]Includes on-chip PLL

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Design Challenges for Modulator TX

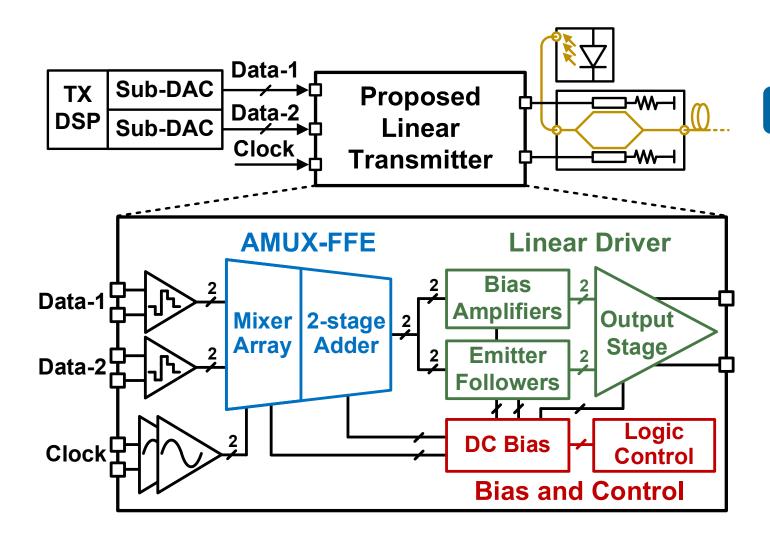
- Large output swing for high optical extinction ratio
- High linearity to support advanced modulation schemes for high data rate
- High bandwidth to increase the link speed
- Equalization to compensate for high-frequency loss from E/E and E/O interfaces



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Architecture Design



AMUX-FFE

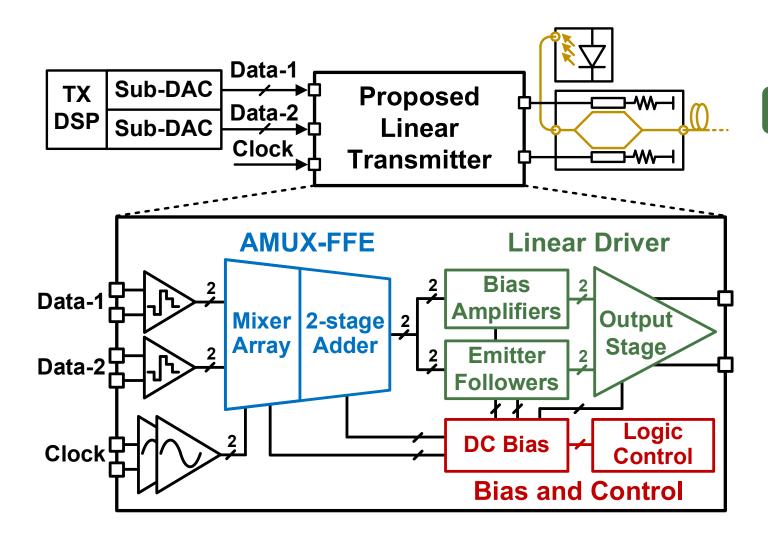
Analog serialization

 Serializes analog data streams from half rate to full rate

Equalization

- Generates equalized signal with a re-configurable FFE
- No tap generator required to save power

Architecture Design



Linear Driver

Large output swing

 Adopts a dynamic triple-stacked (DTS) topology to achieve large output swing without breakdown

High linearity

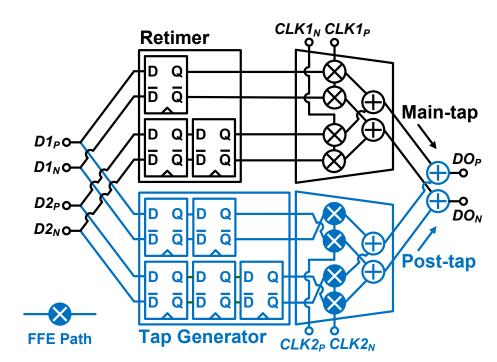
 The DTS topology also provides high linearity by decreasing V_{CE} variations of HBTs

Comparison btw Conv. and Prop. AMUX-FFEs

Conventional AMUX-FFE

Uses latches to generate FFE tap

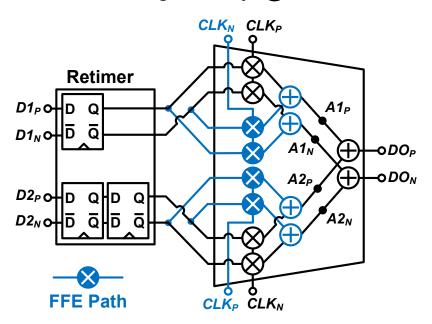
- High hardware & power overhead
- Bad re-configurability (2)



Proposed AMUX-FFE

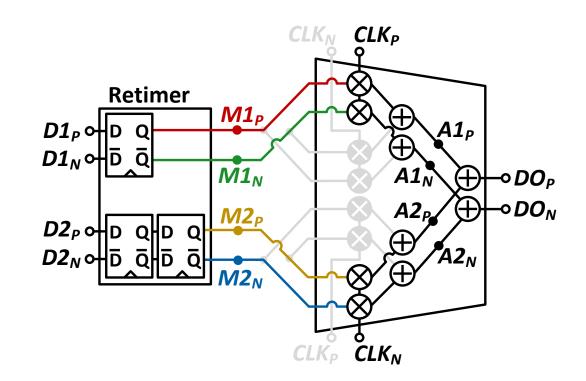
Uses re-timed differential data streams to generate FFE tap

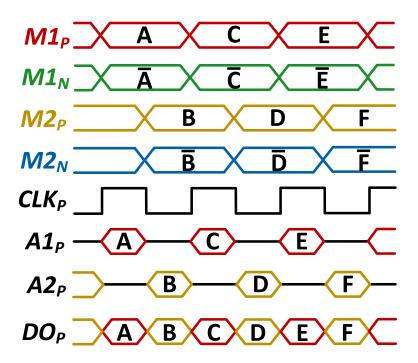
- Low hardware & power overhead
- Good re-configurability ⁽²⁾



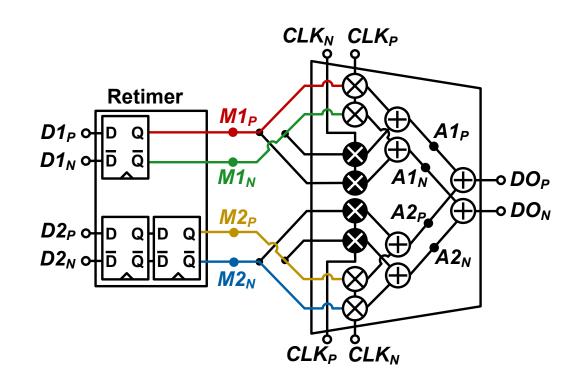
CONFIG-1: FFE Turned OFF

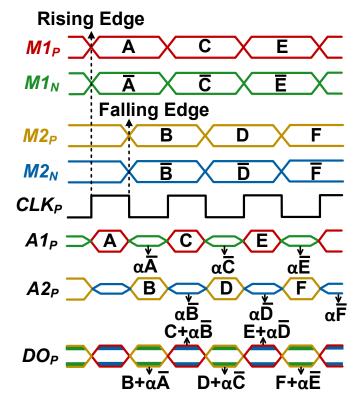
When mixers of four FFE paths are turned off, the AMUX functions as a normal 2-to-1 serializer



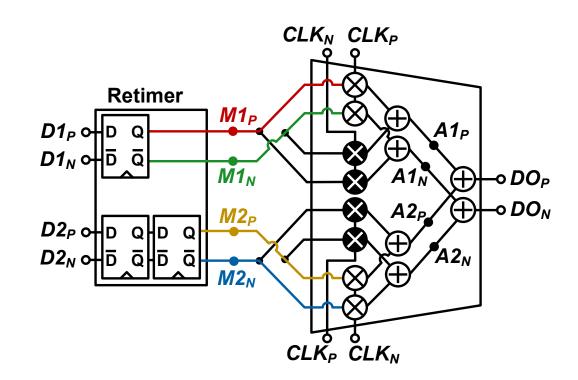


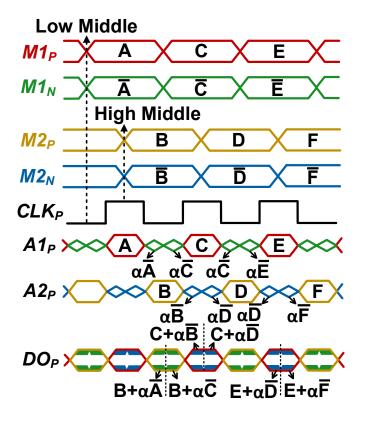
CONFIG-2: 1 Main + 1 Post DO_P is the same with the output of a FFE with 1 main tap and 1 post-tap, tap spacing = 1 UI



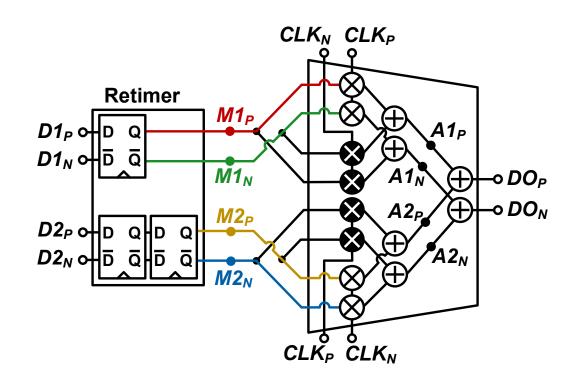


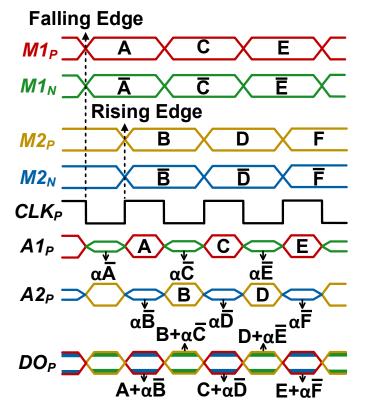
CONFIG-3: 1 Main + 1 Pre + 1 Post DO_P is the same with the output of a FFE with 1 pre-tap, 1 main tap and 1 post-tap, tap spacing = 0.5 UI



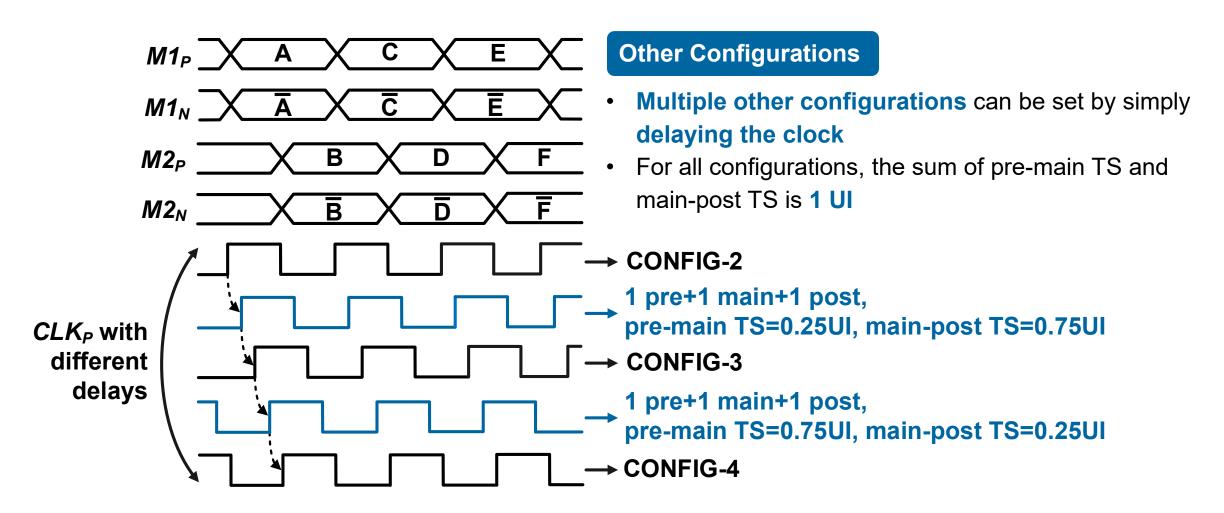


CONFIG-4: 1 Main + 1 Pre DO_P is the same with the output of a FFE with 1 pre-tap and 1 main tap, tap spacing = 1 UI

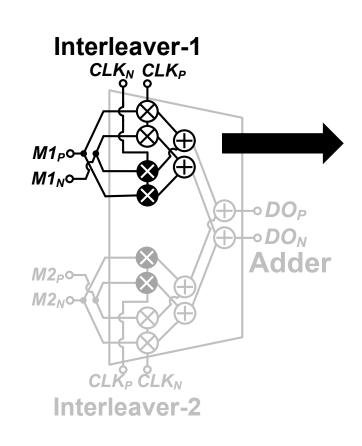


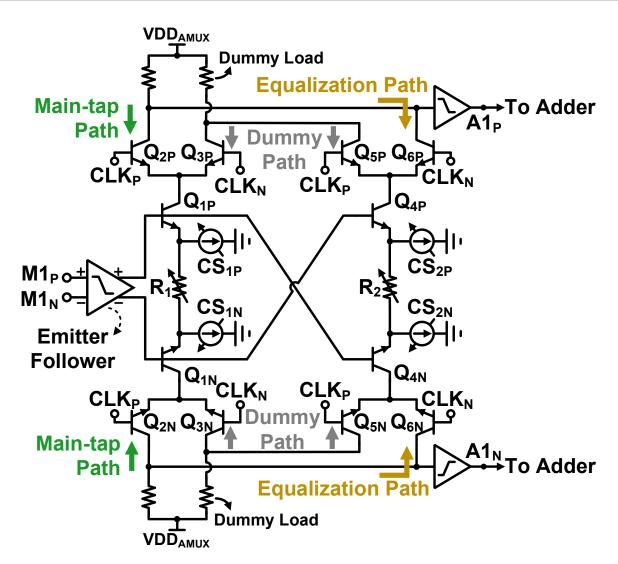


Principle of the AMUX-FFE

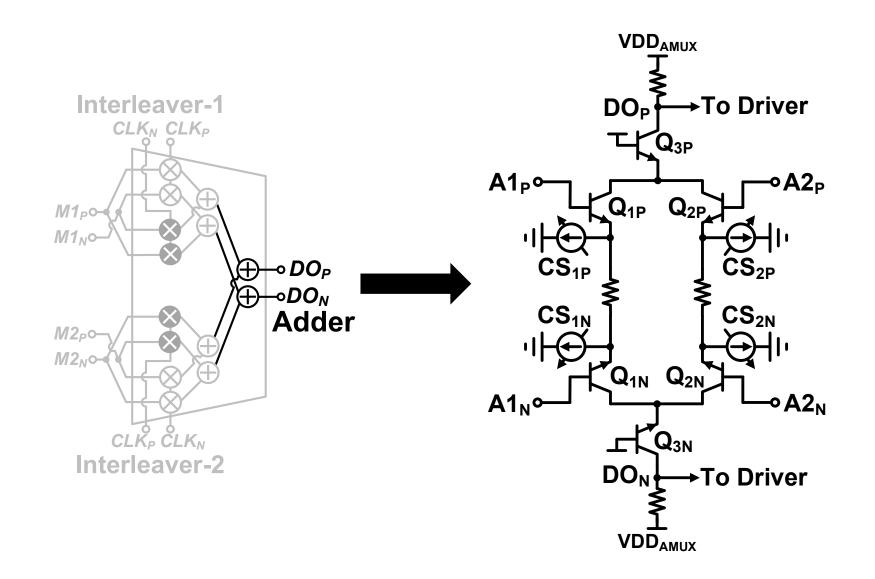


Schematic of the AMUX-FFE





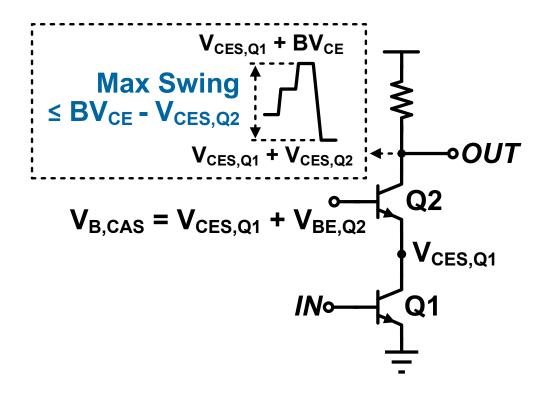
Schematic of the AMUX-FFE



Comparison Between Driver Topologies

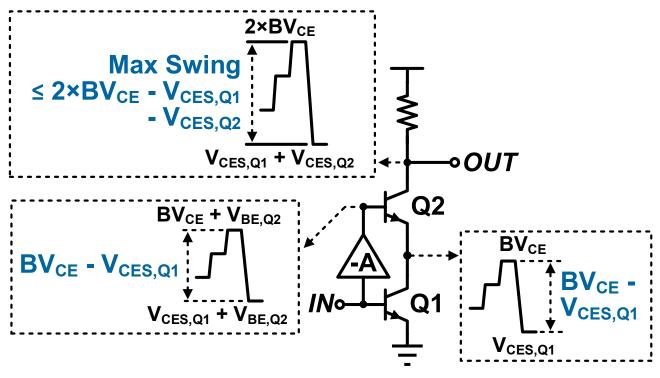
Conventional Cascode

Limited output voltage swing

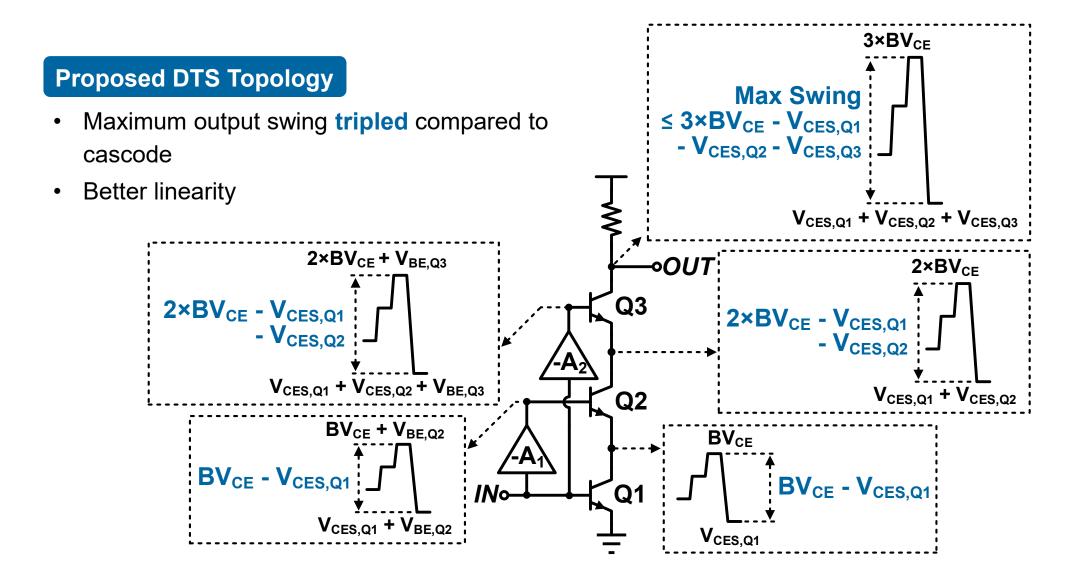


Breakdown Voltage (BV) Doubler

Maximum output swing doubled

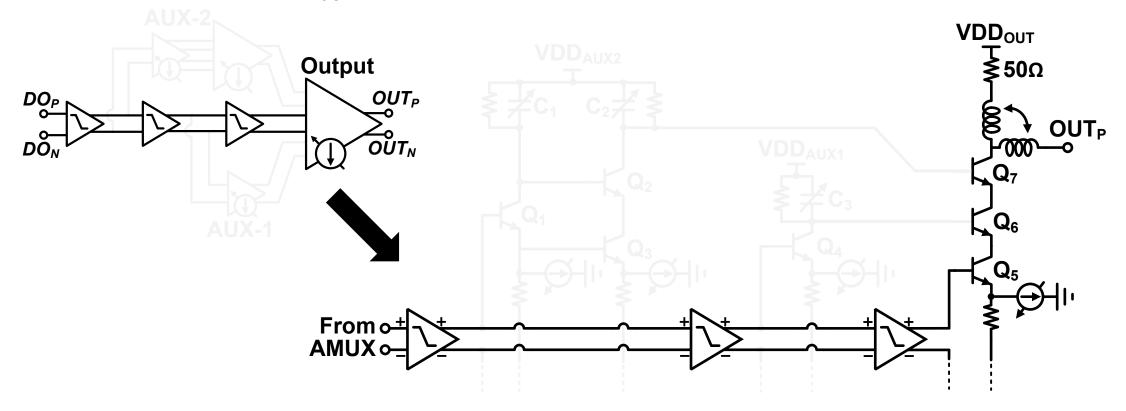


Comparison Between Driver Topologies



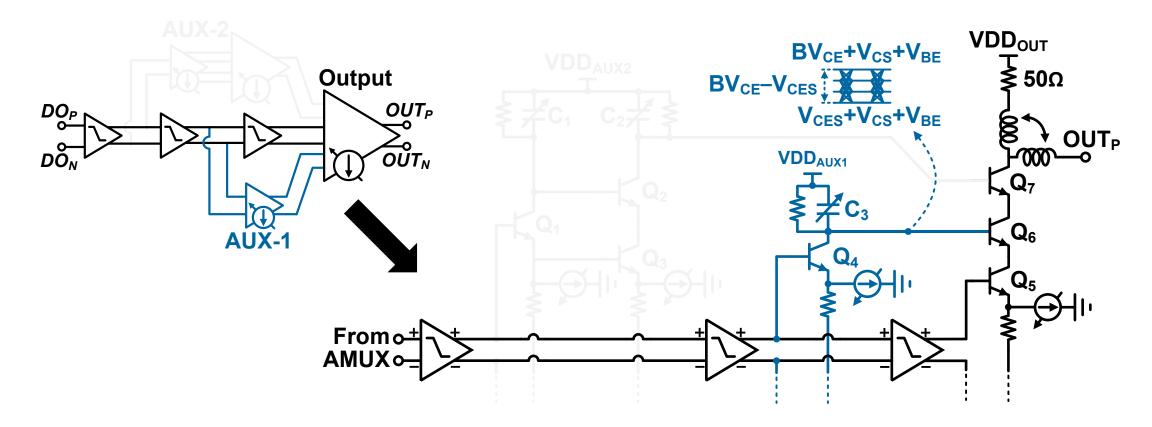
Main Path

- Three emitter followers for ensuring appropriate DC conditions for main path,
 AUX-1 path, and AUX-2 path and buffering signals
- $VDD_{OUT} = 6.5 V$



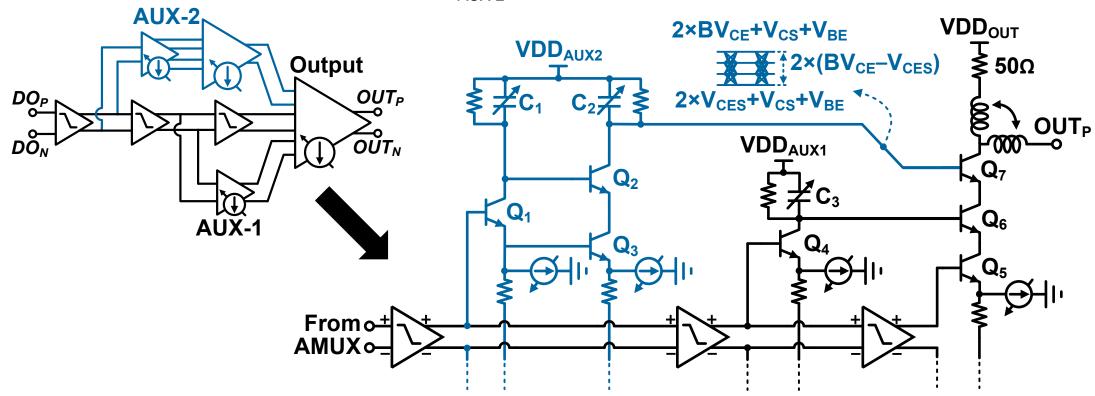
AUX-1 Path

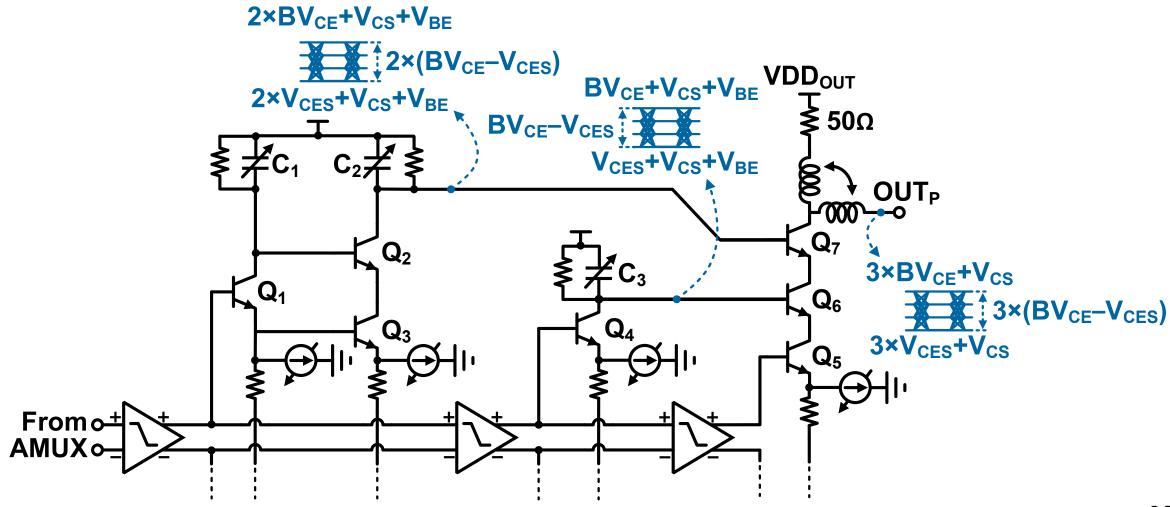
- AUX-1 path for dynamically biasing the base of Q₆
- VDD_{AUX-1} = 3.5 V



AUX-2 Path

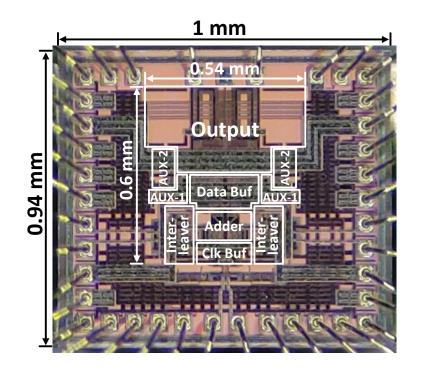
- AUX-2 path for dynamically biasing the base of Q7
- AUX-2 itself is a BV doubler
- $VDD_{AUX-2} = 4.5 V$

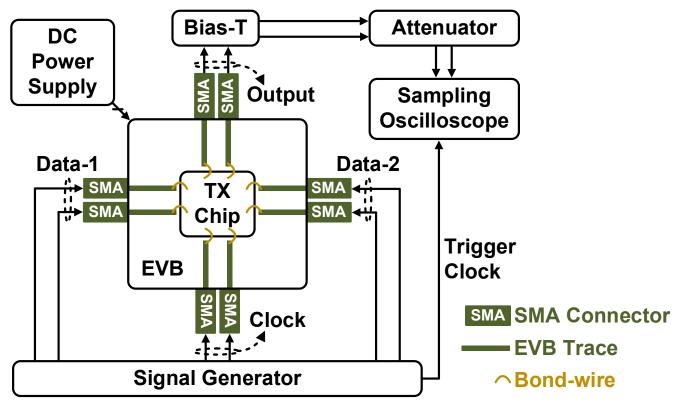




Design Under Test

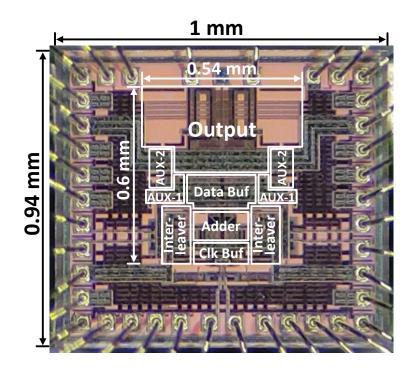
- The transmitter is fabricated in **130-nm SiGe BiCMOS** with f_T/f_{max} of 250/340 GHz
- All signals are wire-bonded to the EVB for measurement

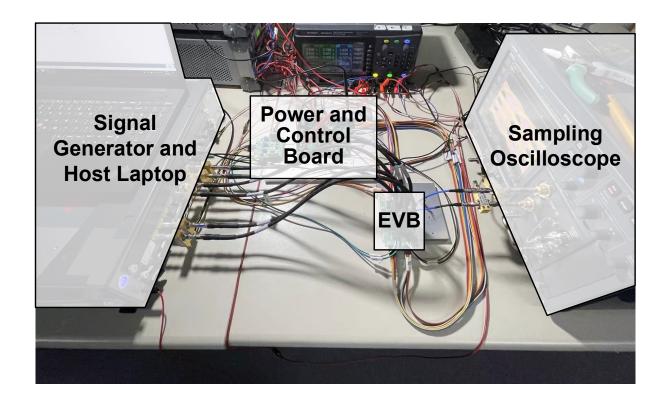




Design Under Test

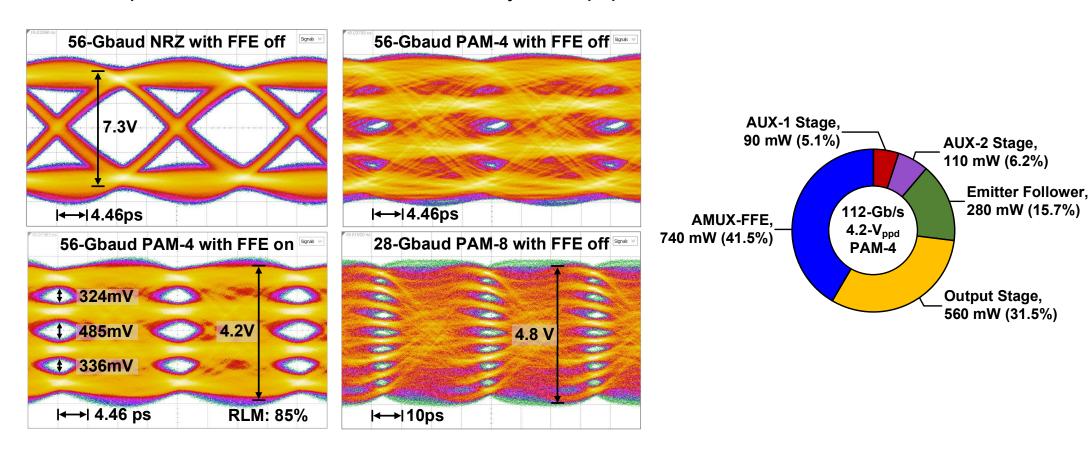
- The transmitter is fabricated in **130-nm SiGe BiCMOS** with f_T/f_{max} of 250/340 GHz
- All signals are wire-bonded to the EVB for measurement





Measurement Results

- The whole transmitter supports a maximum output swing of 7.3 V_{ppd} @ 56-Gbaud NRZ
- With FFE, 56-Gbaud 4.2-V_{ppd} PAM-4 is achieved, with 1.78-W power consumption
- The speed of the PAM-8 case is limited by the equipment



Comparison with Prior Works

		[8] TMTT'17	[9] JSSC'20	[10] BCICTS'21	[11] BCICTS'22	[7] This Work
Technology		130-nm SiGe BiCMOS	130-nm SiGe BiCMOS	130-nm SiGe BiCMOS	130-nm SiGe BiCMOS	130-nm SiGe BiCMOS
f _T / f _{MAX} [GHz]		300/500	250/NA	300/500	380/520	250/340
Туре		Distributed, Linear	Lumped, Linear	Distributed, Linear	Lumped, Linear	Lumped, Linear
Output Impedance Matching [Ω]		100	100	100	100	100
Equalization		NA	NA	1-tap FFE	NA	Reconfig. FFE
Serialization		NA	NA	NA	NA	2:1 Analog
Maximum Ouput Swing [V _{ppd}]		4 @90-Gb/s PAM-4	6 @64-Gb/s NRZ	4 @64-Gb/s Duobinary	2 (estimated by P1dB)	7.3 @56-Gb/s NRZ
Maximum Data Rate [Gb/s]		120 @3-V _{ppd} NRZ	138 @2.4-V _{ppd} PAM-4	64 @4-V _{ppd} Duobinary	128 @1.2-V _{ppd} PAM-4	112 @4.2-V _{ppd} PAM-4
Data Rate-Output Swing Product [V·Gb/s]		360	384	256	256	470
Driver THD		3.8% @1GHz, 3V _{ppd}	3.6% @1GHz, 6V _{ppd}	5.5% @1GHz, 4V _{ppd}	6% @5GHz, 2V _{ppd}	1.6% @1GHz, 6V _{ppd}
Driver Gain [dB]		12.5	30 (with VGA)	24	18	17
Area [mm²]		1.2	1.6	1.5	0.55	0.9
Power Consumption [mW]	Driver	550	1000	1030	280	1040
	AMUX	NA	NA	NA	NA	740
FoM# [bit/s/Hz]		0.00818	0.00397	0.00414	0.00217	0.00867

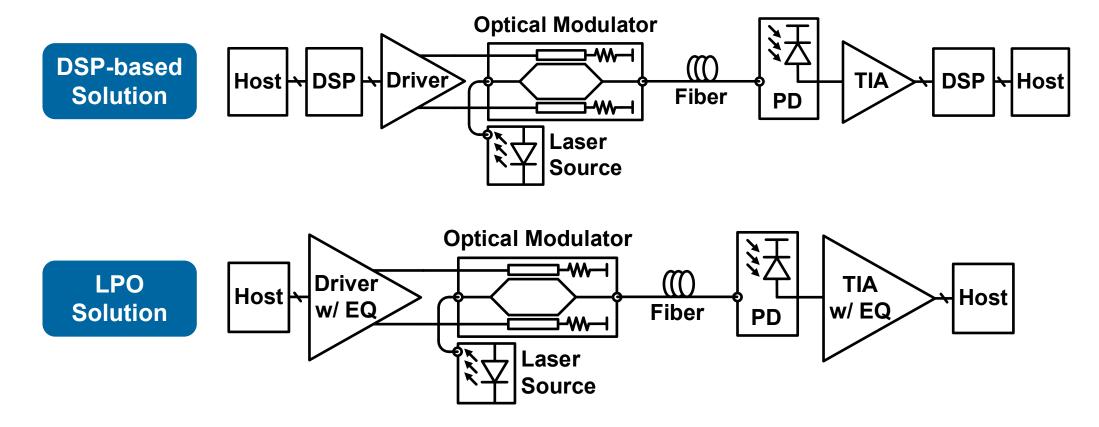
#FoM = $\frac{\text{Maximum Data Rate}}{f_T}$ · $\frac{(\text{Output Swing @ Maximum Data Rate})^2}{8 \cdot \text{Output Impedance Matching} \cdot \text{Power Consumption}}$

Outline

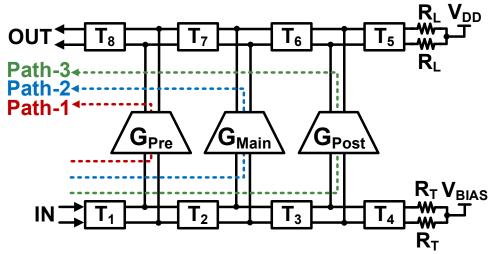
- Background
- Transmitter Design for VCSEL-based Optical Links
 - Imperfections of VCSEL
 - Implementation and Measurement of A 56-Gb/s PAM-4 VCSEL Transmitter
- □ Transmitter Design for Optical Modulator-based Optical Links
 - Design Challenges
 - Implementation and Measurement of A 56-Gbaud Half-rate Linear Transmitter
 - Implementation and Measurement of A 100-Gbaud Linear Modulator Driver
- Conclusions

Motivation

- For medium-reach optical communications, linear pluggable optics (LPO) outperforms DSPbased solutions in terms of energy efficiency, cost and latency
- However, how to implement EQ in driver? How to increase the link speed?



Motivation



P M

TL-based Equalizer

Pre-to-main Spacing = Delay_{Path-2} - Delay_{Path-1}
Main-to-post Spacing = Delay_{Path-3} - Delay_{Path-2}

- Good EQ capability
- Small swing and low gain

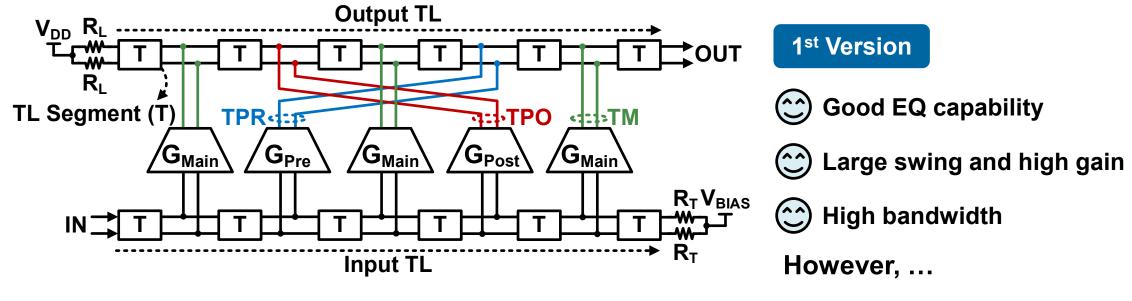
V_{DD} R_L T_8 T_7 T_6 T_5 OUT R_L Path-1 Path-2 Path-3 G_{m1} G_{m2} G_{m3} R_T V_{BIAS} R_T

Distributed Amplifier

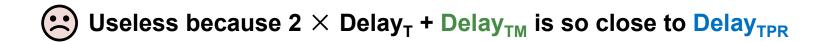
 $Delay_{Path-1} = Delay_{Path-2} = Delay_{Path-3}$

- **C** Large swing and high gain
- **◯** No EQ

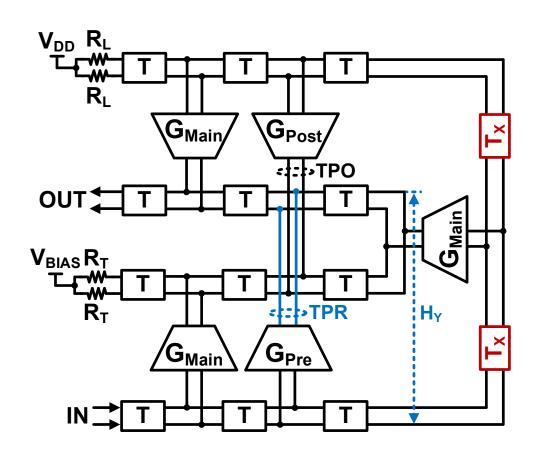
Architecture Design Evolution (1st Vesion)



- Main-to-post Spacing = 2 × Delay_T + Delay_{TPO} Delay_{TM}
- Pre-to-main Spacing = 2 × Delay_T + Delay_{TM} Delay_{TPR}



Architecture Design Evolution (2nd Version)



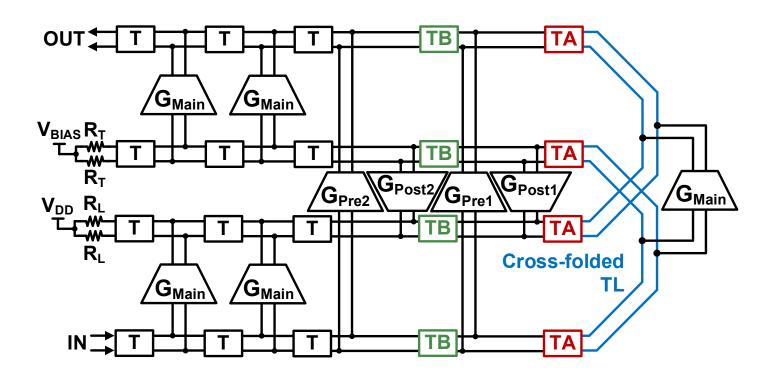
2nd Version

- Good EQ capability
- **Example 2** Large swing and high gain
- Delay_{TPR} can be smaller by minimizing H_Y to increase pre-to-main spacing

However, ...

igoplus A length discrepancy of $2 \times T_X$ between input and output TL is introduced

Architecture Design Evolution (Final Scheme)

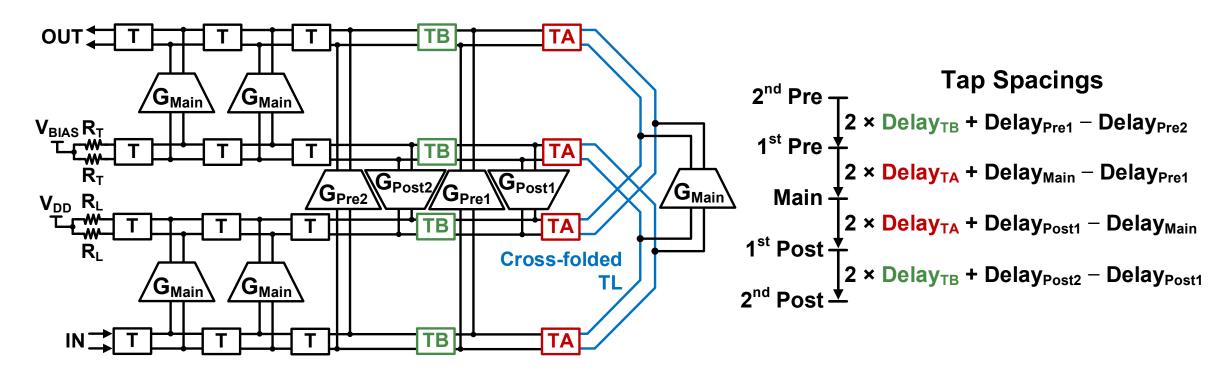


Final Scheme

- Good EQ capability
- **C** Large swing and high gain
- Pre-to-main and Main-to-post spacings can be properly set
- No discrepancy between the lengths of input and output TLs

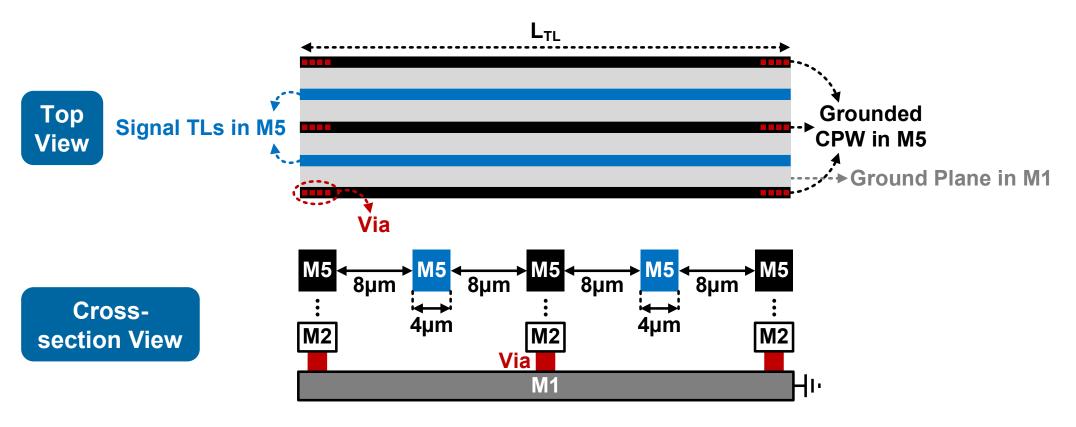
Architecture Design Evolution (Final Scheme)

- The tap spacings can be designed by adjusting the length of related TL segment
- In the future, the FFE Gm cells can be designed to be controllable delay cell



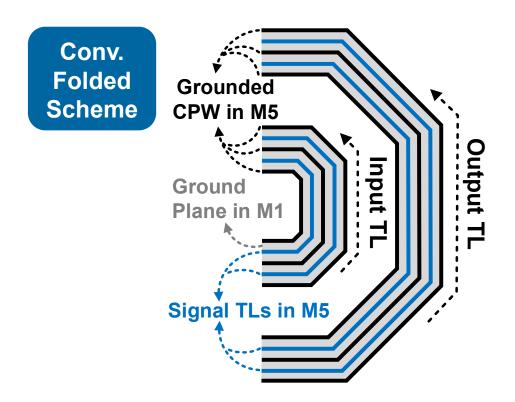
Implementation of TL Segments

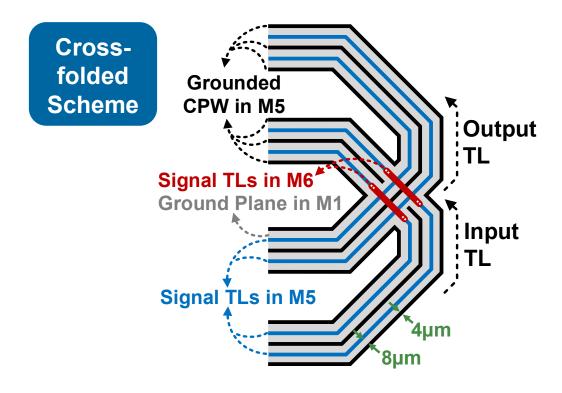
- Differential signals delivered in metal-5 (M5) and shielded by three grounded CPW also in M5
- Ground plane in metal-1 (M1) implemented for substrate shielding



Implementation of Cross-folded TL

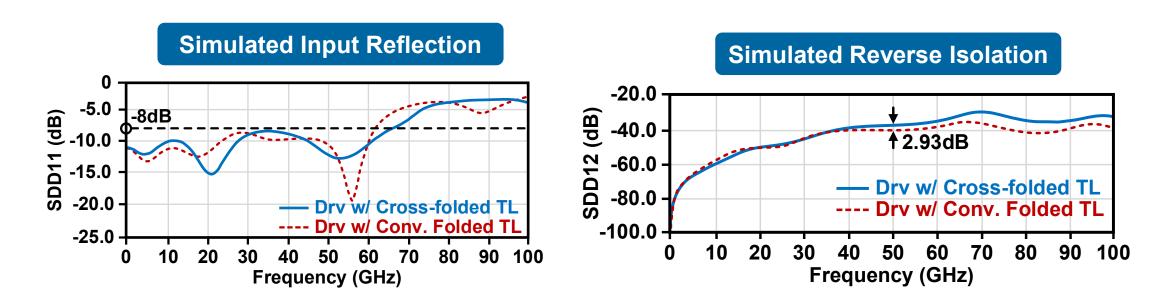
- A cross-folded scheme to balance the lengths of input and output TLs
- Input TL jumps from M5 to M6 and then back to M5, which may bring some degradations





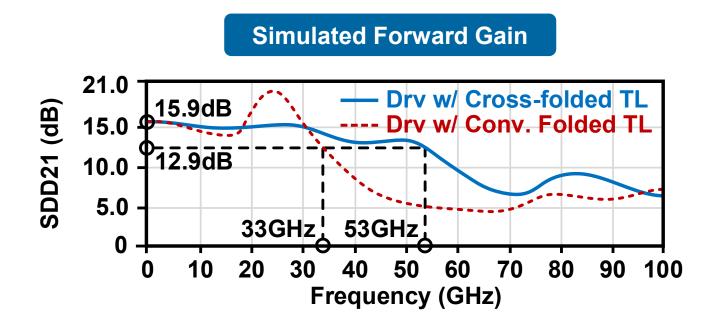
Implementation of Cross-folded TL

- The intersection results in the discontinuity of the input impedance which may degrade the input reflections
- The intersection aggravates the parasitic effect between input and output TLs which may degrade the inverse isolation

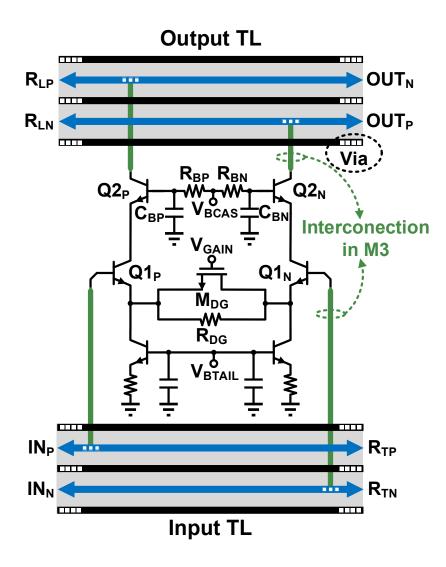


Implementation of Cross-folded TL

 With much smaller discrepancies between the lengths of input and output TLs, the cross-folded scheme achieves much better in-band gain response and higher 3-dB bandwidth



Schematic of the Gm Cell

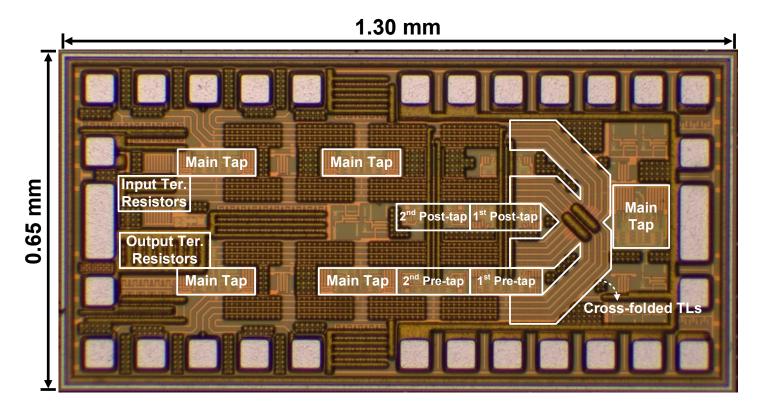


Design of Gm Cell

- All the main-tap and FFE-tap Gm cells adopt the same design
- A cascode topology is selected to improve the breakdown voltage
- R_{DG} for linearity enhancement
- M_{DG} for gain tunning
- The Gm cells are connected to the input and output TLs using metal-3 (M3) layer

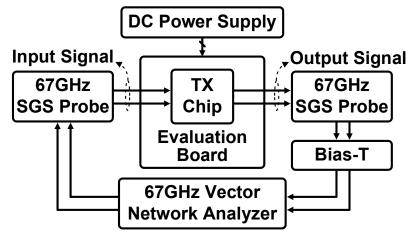
Design Under Test

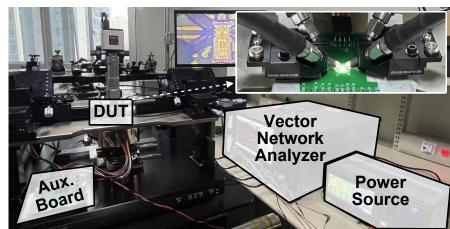
- The distributed driver is fabricated in **130-nm SiGe BiCMOS** with f_T/f_{max} of 250/340 GHz
- The RF signals are probed using 67-GHz SGS probe during measurement
- All other signals are wire-bonded to the evaluation board



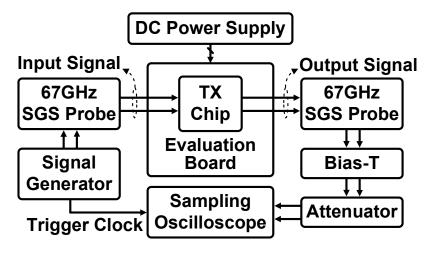
Measurement Setups

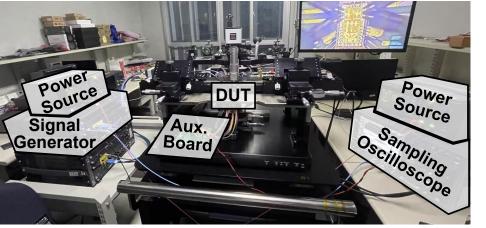
Frequency-domain Measurement





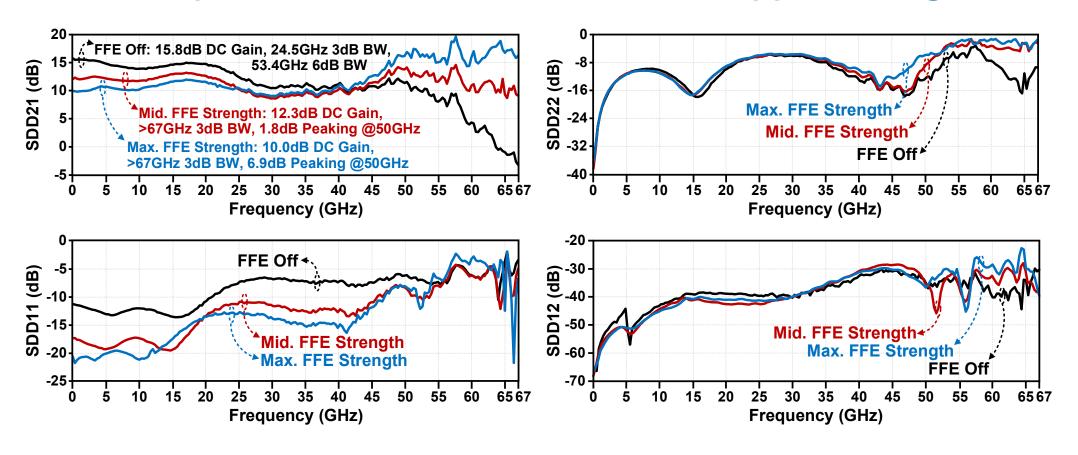
Time-domain Measurement





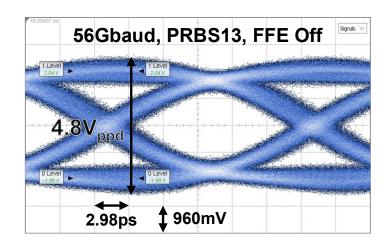
Measurement Results

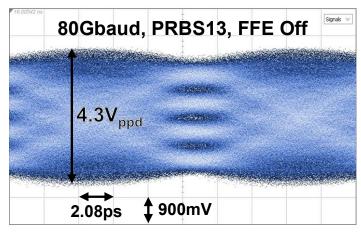
- With FFE off, a DC gain of 15.8dB, a 3-dB BW of 24.5GHz, and a 6-dB BW of 53.4GHz are achieved
- With FFE on, a DC gain of 10dB, a 3-dB BW of >67GHz, and a peaking gain of 6.9dB@50GHz are achieved

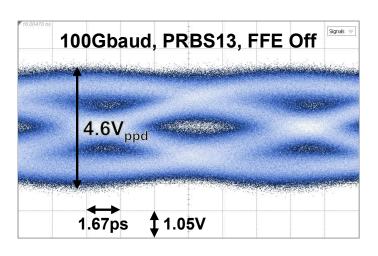


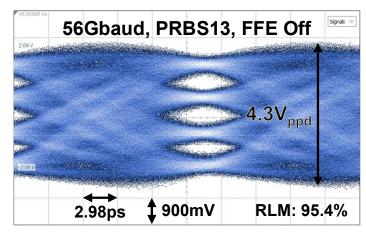
Measurement Results

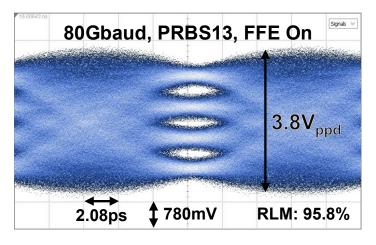
The driver is capable of outputting 3.8-V_{ppd} 160-Gb/s PAM-4 and 4.0-V_{ppd} 100-Gb/s NRZ signals

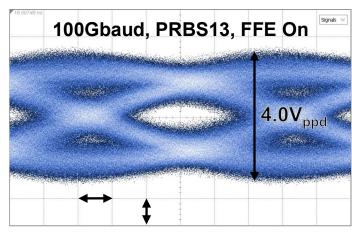












Comparison with Prior Works

	[8]TMTT'17	[9] JSSC'20	[7] CICC'24	[13] TMTT'24	[12] This Work
SiGe Node (nm)	130	130	130	55	130
f _T / f _{MAX} (GHz)	300/500	250/NA	250/340	330/370	250/340
Topology Type	Distributed	Lumped	Lumped	Hybrid	Distributed
Equalization in Driver	No	No	No	No	5-tap FFE
3-dB Bandwidth (GHz)	90	>40	38	>70	>67
Maximum Data Rate (Gb/s)	120 @3V _{ppd} NRZ	138 @2.4V _{ppd} PAM-4	112 @4.2V _{ppd} PAM-4	256 @3.4V _{ppd} PAM-4	160 @3.8V _{ppd} PAM-4
THD	<5.00% @1GHz, 3V _{ppd}	3.60% @1GHz, 6V _{ppd}	1.60% @1GHz, 6V _{ppd}	<2.00% @1GHz, 3.6V _{ppd}	2.21% @5GHz, 4V _{ppd}
DC Gain (dB)	12.5	30.0	17.0	11.2~21.8	10.0~15.8
Supply (V)	5.5	5.5	NA	3.0/4.0	4.8
Power (mW)	550	1000	1040	725	612
Area (mm²)	1.19	1.60	0.66	1.07	0.85
Z _o (ohm)	100	100	100	100	100
*FoM (bit/s/Hz)	0.008	0.004	0.009	0.016	0.019

*FoM = $\frac{\text{Maximum Data Rate}}{f_{\text{T}}} \cdot \frac{(\text{Output Swing @ Maximum Data Rate})^2}{8 \cdot Z_o \cdot \text{Power Consumption}}$

Outline

- Background
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 - Implementation and Measurement of A 100-Gbaud Linear Modulator Driver
- □ Conclusions

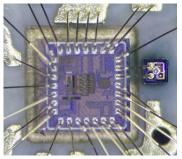
Conclusions

For multi-mode optical links

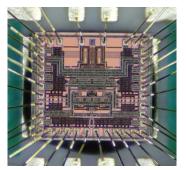
 Proposes a VCSEL transmitter with piecewise compensation scheme, effectively enhances the optical eye opening, achieves 56-Gb/s PAM-4 with 2.05-pJ/bit energy efficiency

For single-mode optical links

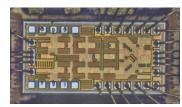
- Proposes a linear modulator transmitter with AMUX-FFE and large-swing driver, achieves 2-to-1 analog serialization, reconfigurable 3-tap FFE, 7.3-V_{ppd} maximum swing, and 4.2-V_{ppd} 112-Gb/s PAM-4 outputs
- Proposes a linear distributed modulator driver with cross-folded transmission lines and cross-coupled Gm cells, achieves 5-tap built-in FFE and 3.8-V_{ppd} 160-Gb/s PAM-4 output



ESSCIRC'23

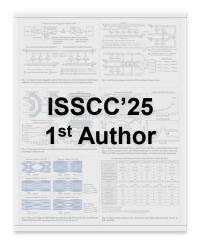


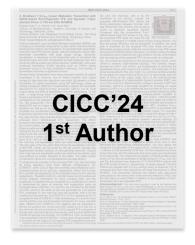
CICC'24



ISSCC'25

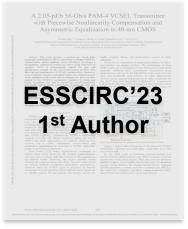
Research Outcomes

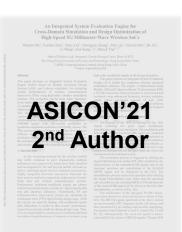




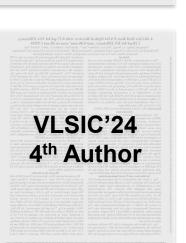
APCCAS'22

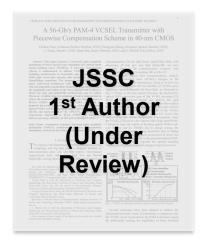
2nd Author

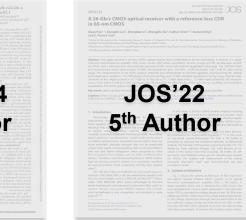












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- My parents







Q & A

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Optical Wireless Lab

Department of Electronic and Computer Engineering

The Hong Kong University of Science and Technology (HKUST)

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- [9] A. H. Ahmed *et al.*, "A Dual-Polarization Silicon-Photonic Coherent Transmitter Supporting 552 Gb/s/wavelength," in *IEEE Journal of Solid-State Circuits*, vol. 55, no. 9, pp. 2597-2608, Sept. 2020.
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